The present invention is easily distinguished from Ohie for the following reasons. Ohie does not disclose, at a minimum, "a third bonding wire for connecting the third bonding pad on the second semiconductor chip with the inner lead portion of the first lead". As shown in Fig. 18 of Ohie, a first bonding wire 7 connects a first bonding pad on a first semiconductor chip with the inner lead portion of a first lead. A plurality of second bonding wire 17 connect plural second bonding pads on the first semiconductor chip with inner lead portions of plural second leads. However, there is no third bonding wire 17 which connects a third bonding pad on the second semiconductor chip with the inner lead portion of the first lead.

In other words, none of the inner lead portions of the first leads are connected to <u>both</u> a bonding wire from the first semiconductor chip and a bonding wire from the second semiconductor chip. As clearly shown in Fig. 18, bonding wires from the first semiconductor chip and the second semiconductor chip are connected to different inner lead portions.

On the other hand, according to the present invention, a signal interconnection between a control chip and a memory chip can be achieved by selecting a single lead of a lead-frame. This obviates the need for various kinds of lead

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frames and/or a special control chip having extra bonding pads. As a result, the overall cost of the package can be reduced.

The features and attending advantages of the present invention are neither disclosed nor suggested by Ohie. As such, it is submitted that the pending claims patentably define the present invention over Ohie. The Examiner is hereby invited to contact the undersigned by telephone if any further clarification is needed.

Conclusion

In view of the foregoing amendments and remarks,

Applicants contend that the above-identified application is

now in condition for allowance. Accordingly, reconsideration

and reexamination are respectfully requested.

Respectfully submitted,

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